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3/15/02



Box Patent Applications
Assistant Commissioner for Patents
Washington DC 20231

Enclosed for filing are the following patent application papers:

Docket No. : DP-305031

Inventor(s) : Shing Yeh
Bradley H. Carter
Curtis W. Melcher

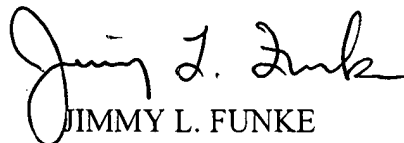
Title : LEAD-FREE SOLDER ALLOY AND SOLDER REFLOW PROCESS

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Very Truly Yours,


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Enclosures

I hereby certify that this document is being deposited with the United States Postal Service with sufficient postage as Express Mail addressed to Box Missing Parts, Assistant Commissioner for Patents, Washington, D.C. 20231 on March 15, 2002. Express Mail Label EK877647791US

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